

# 客户图

## NOTES:

- 1.FINISH:
- 1.1 HOUSING: Polyester(LCP),UL94 V-0
  - 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, TIN PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.
- 2.ELECTRICAL:
- 2.1 CURRENT RATING: 2.0 AMP,AC/DC
  - 2.2 VOLTAGE RATING: 225V AC/318V DC.
  - 2.3 DIELECTRIC WITHSTANDING VOLTAGE: 500V,AC/Minute
  - 2.4 CONTACT RESISTANCE: 20mΩ MAX.
  - 2.5 INSULATION RESISTANCE: 1000 mΩ Min
  - 2.6 Operation Temperature: -40°C to +105°C
- 3.SALT SPRAY TEST:
- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.Max Processing Temp:265°C Seconds 10S
- 5.ORDER INFORMATION:

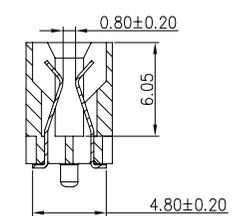
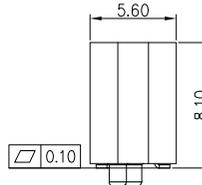
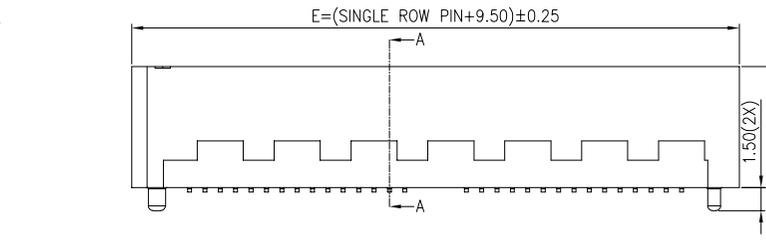
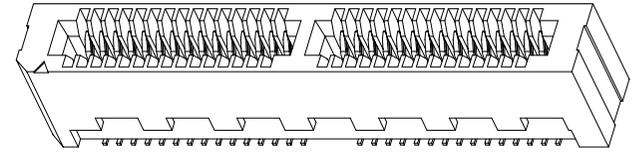
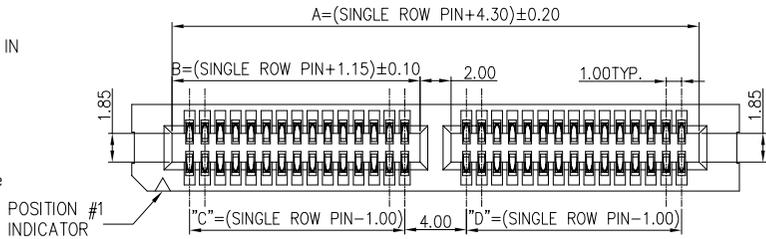
61D3-F XXX XX 078 C XXX-01

F=母座  
"C" PIN数:  
002=2x1PIN  
.....  
100=2x50PIN

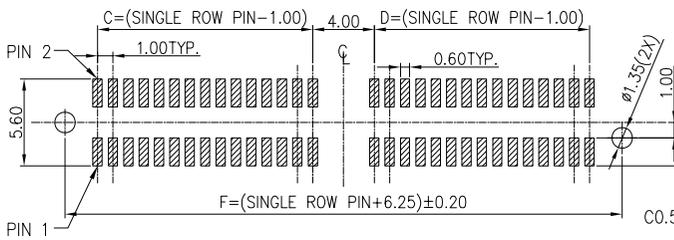
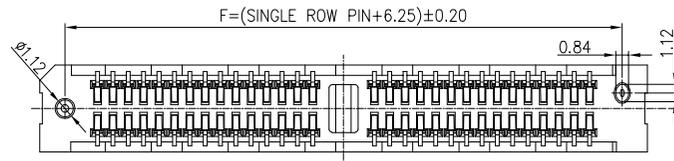
端子电镀:  
S0=Gold Flash/Tin(半金锡)  
S1=1u" Gold/Tin  
S2=3u" Gold/Tin  
S3=5u" Gold/Tin  
S4=10u" Gold/Tin  
S5=15u" Gold/Tin  
S6=30u" Gold/Tin

"D" PIN数:  
002=2x1PIN  
.....  
100=2x50PIN

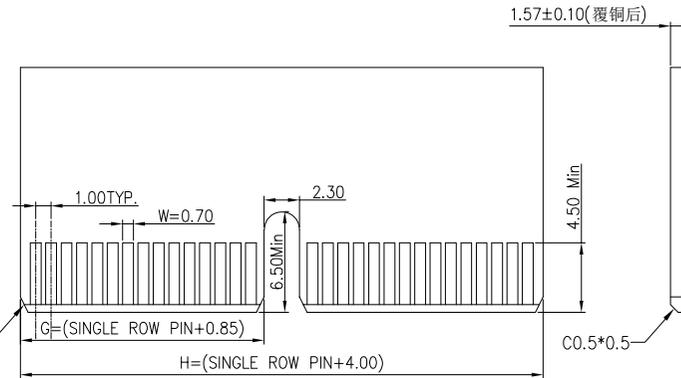
塑胶高度:  
078=7.80mm



SECTION: A-A



RECOMMENDED PCB LAYOUT(BOTTOM SIDE)  
PCB BOARD TOLERANCE±0.05



RECOMMENDED PCB LAYOUT(TOP SIDE)  
PCB BOARD TOLERANCE±0.05

					OPERATION	DRAW	Mr.Zeng	2025.03.26
					X.X ±0.40	DESIGN	Jensen	2025.03.26
					X.XX ±0.25	CHECK	Jack	2025.03.26
					X.XXX ±0.15	APPROVE	Andy	2025.03.26
A0		NEW			Angle ±3°			
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm
							SCALE	1:1

**SOLEPIN** 东莞市硕品电子有限公司  
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	61D3-F XXX XX 078 C XXX-01
SHEET	1/1	TITLE:	1.0mm 金手指 SMT 180° TYPE 带隔栏/带定位柱
PROJ.	☺	DRAW NO.	SP-1461

# 客户图

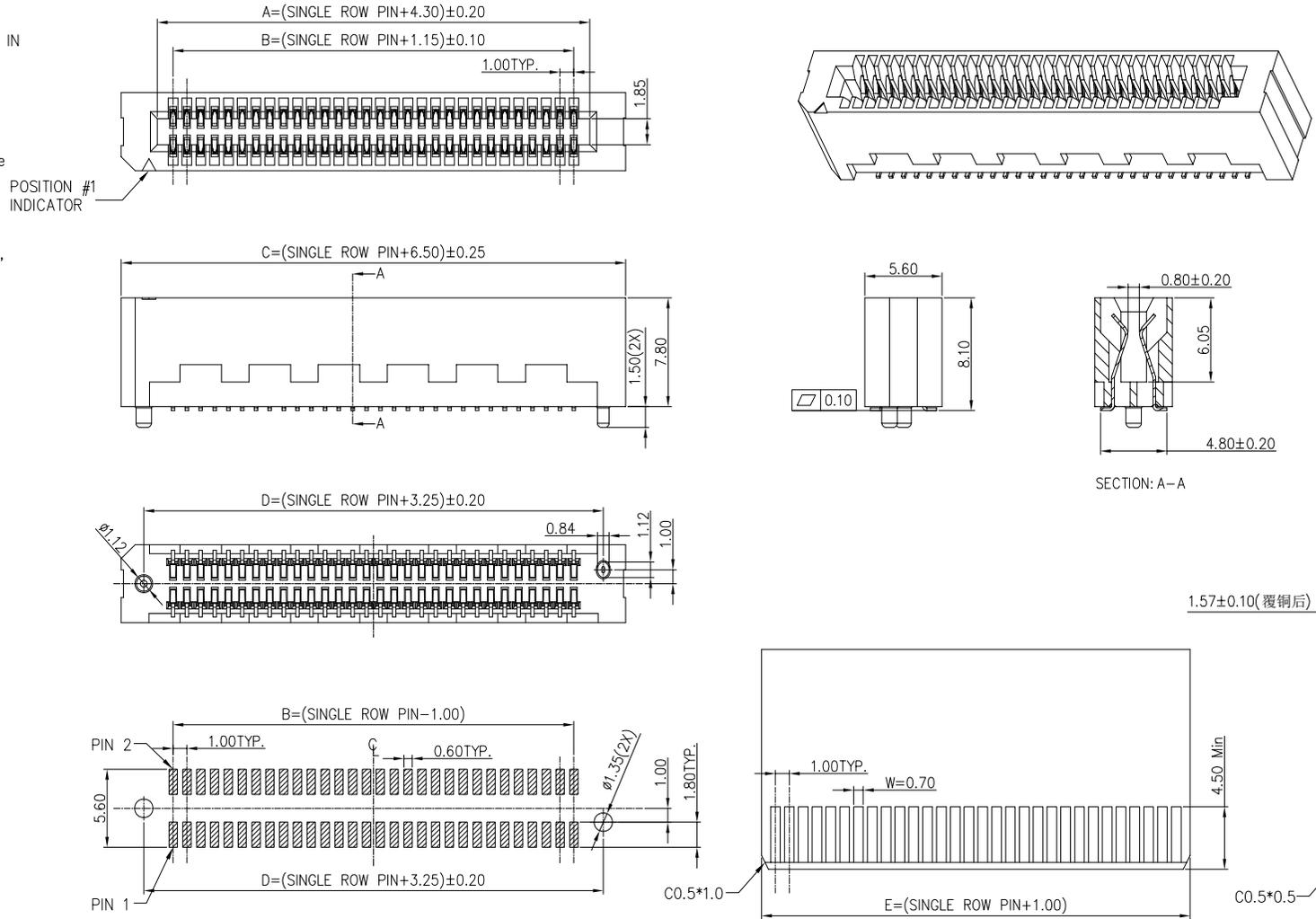
NOTES:

- 1.FINISH:  
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 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, TIN PLATED IN SOLDER AREA, 50u"MIN NICKEL UNDERPLATED OVERALL.
- 2.ELECTRICAL:  
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 2.4 CONTACT RESISTANCE: 20mΩ MAX.  
 2.5 INSULATION RESISTANCE: 1000 mΩ Min  
 2.6 Operation Temperature: -40°C to +105°C
- 3.SALT SPRAY TEST:  
 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C, TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.Max Processing Temp:265°C Seconds 10S
- 5.ORDER INFORMATION:

61D3-F XXX XX 078 C 02  
 F=母座  
 端子电镀:  
 S0=Gold Flash/Tin(半金锡)  
 S1=1u" Gold/Tin  
 S2=3u" Gold/Tin  
 S3=5u" Gold/Tin  
 S4=10u" Gold/Tin  
 S5=15u" Gold/Tin  
 S6=30u" Gold/Tin

塑胶高度:  
 078=7.80mm

PIN数:  
 002=2x1PIN  
 .....  
 200=2x100PIN



RECOMMENDED PCB LAYOUT(BOTTOM SIDE)  
 PCB BOARD TOLERANCE±0.05

RECOMMENDED PCB LAYOUT(TOP SIDE)  
 PCB BOARD TOLERANCE±0.05

					OPERATION	DRAW	Mr.Zeng	2025.03.26	<b>SOLEPIN 东莞市硕品电子有限公司</b> <b>PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.</b>			
					X.X ±0.40	DESIGN	Jensen	2025.03.26				
					X.XX ±0.25	CHECK	Jack	2025.03.26	SIZE	A4	PART NO.	61D3-F XXX XX 078 C 02
					X.XXX ±0.15	APPROVE	Andy	2025.03.26	SHEET	1/1	TITLE:	1.0mm 金手指 SMT 180° TYPE 无隔栏/带定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	SP-1462

# 客户图

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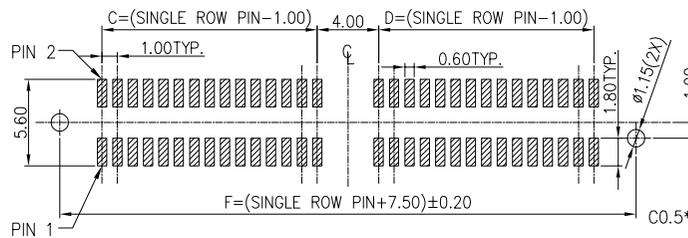
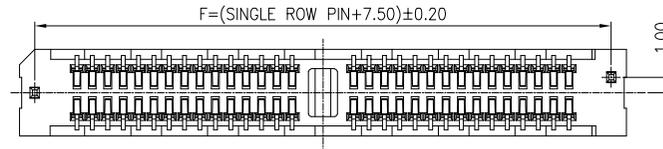
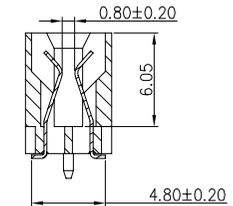
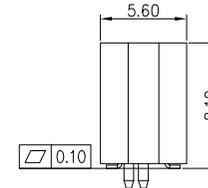
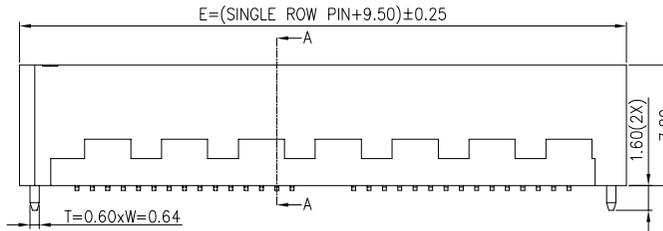
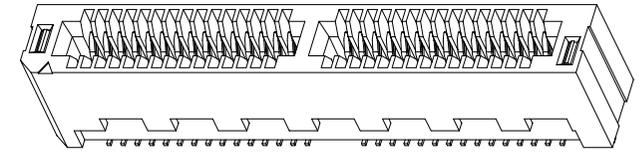
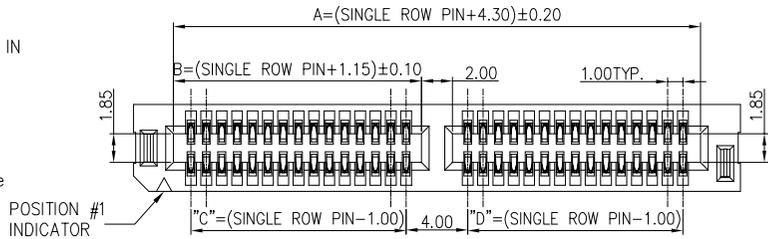
61D3-F XXX XX 078 C XXX-03

F=母座  
"C" PIN数:  
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.....  
100=2x50PIN

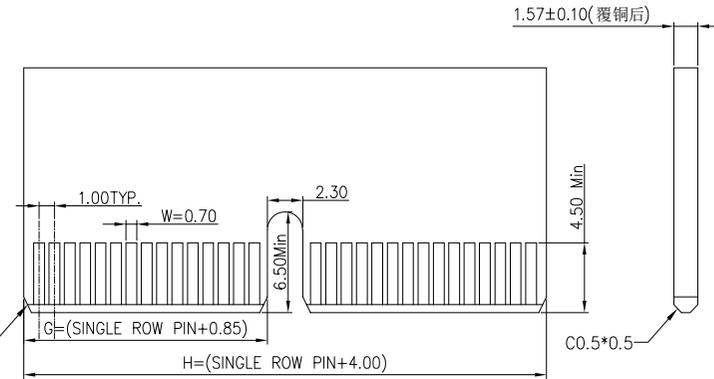
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"D" PIN数:  
002=2x1PIN  
.....  
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塑胶高度:  
078=7.80mm



RECOMMENDED PCB LAYOUT(BOTTOM SIDE)  
PCB BOARD TOLERANCE±0.05



RECOMMENDED PCB LAYOUT(TOP SIDE)  
PCB BOARD TOLERANCE±0.05

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A0				NEW	Angle ±3°			
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT	mm
							SCALE	1:1

**SOLEPIN 东莞市硕品电子有限公司**  
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	61D3-F XXX XX 078 C XXX-03
SHEET	1/1	TITLE:	1.0mm 金手指 SMT 180° TYPE 带隔栏/带接地脚
PROJ.	☯	DRAW NO.	SP-1463

# 客户图

## NOTES:

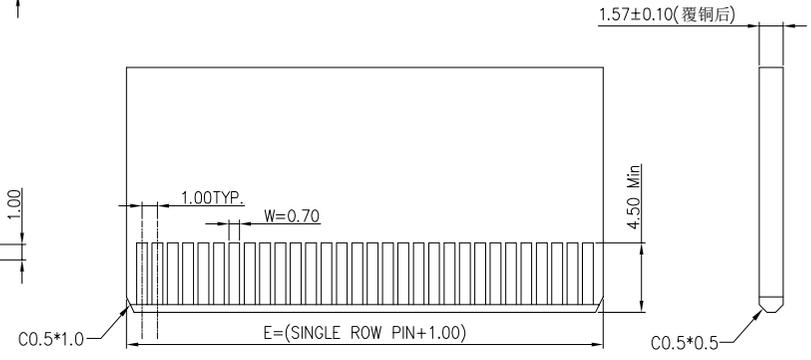
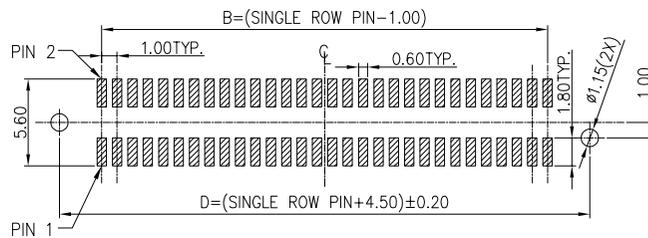
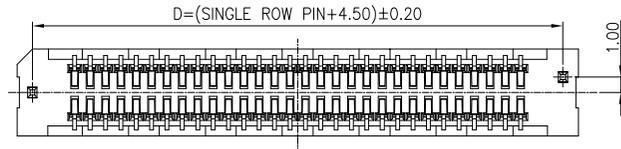
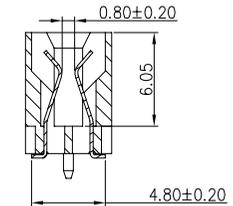
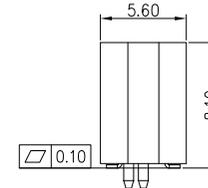
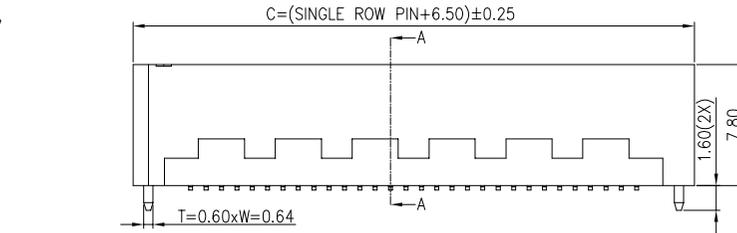
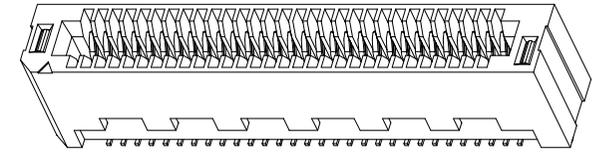
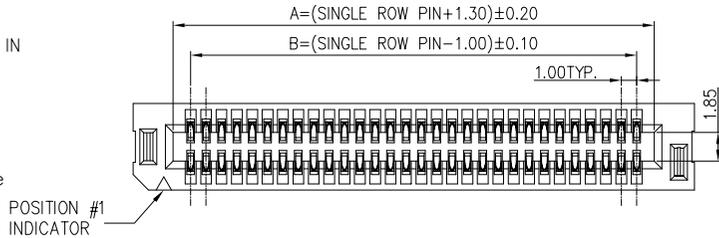
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61D3-F XXX XX 078 C 04

F=母座  
塑胶高度:  
078=7.80mm

PIN数:  
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.....  
200=2x100PIN

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					X.XXX ±0.15	APPROVE	Andy	2025.03.26					
A0				NEW	Angle ±3°				SHEET	1/1	TITLE:	1.0mm 金手指 SMT 180° TYPE 无隔栏/带接地脚	
REV	DATE			MODIFICATION DESCRIPTION	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1464